

DDR5/LPDDR5 CAMM2 Connector

COMPLIES TO JEDEC SO-032 SPEC

The DDR5/LPDDR5 CAMM2 connector follows JEDEC standards with 644 pins, has a pitch of 1.00x1.38mm, and a connector height of 1.0mm. It provides support for dual channel memory capacity of up to 128GB. This connector is developed to support low-power DDR5 memory and does not require ground shielding. Data transmission performance is also improved to 9200MT/s from 8533MT/s for DDR5 and LPDDR5. Another significant advantage is that, the LPDDR5 CAMM2 connector provides users with the flexibility of upgrading and repairing it, compared to the conventional LPDDR5 memory, which was soldered down on the board.



TARGET MARKETS



FEATURES

- Supports faster data rates
- Very low profile
- Compression contacts
- No module insertion
- Matrix form factor
- 1 connector support 128GB
- No need of BGA

BENEFITS

- Faster transition
- Saves system height space
- No insertion and extraction force issue
- No housing crack issue
- Facilitates good airflow
- Provides higher memory capacity
- Easier for upgrading and repairing

TECHNICAL INFORMATION

MATERIAL

- Contacts: Copper Alloy, Gold flash or 15µin min. of Gold or 30µin min. of Gold on contact area, Nickel plating overall (Underplate)
- Insulator: High-temperature, Thermal plastic (UL94V-0), Black color

ELECTRICAL PERFORMANCE

- Current Rating: 1.0A/pin.
- LLCR: 50mΩ max. (initial)
- Withstanding Voltage: 500VAC (at sea level, one minute)
- Insulation Resistance: 1MΩ min.
- Temperature Rise: 30°C max.

MECHANICAL PERFORMANCE

- Durability: 25 cycles
- Vibration, Mechanical Shock
- Reseating: No damage

PACKAGING

- Soft Tray

ENVIRONMENTAL

- Flammability: UL94V-0
- RoHS and Low Halogen

PART NUMBERS

Height	Part Numbers	Pin Count	Type
1.00	CMM5C100X001A	644 Pins	Dual Channel
	CMM5CP001	Top Cover	
	CMM5BP00X	Back Plate	

Find part number details using the search box on www.amphenol-cs.com

APPROVALS & CERTIFICATION

- UL E232356

SPECIFICATIONS

- Amphenol Product Specification: S-DDR-015
- Amphenol Packaging Specification: PKSDDR5009
- Amphenol Application Specification: S-DDR-016
- JEDEC Module Outlines: MO-357/MO-358
- JEDEC Socket Outlines: SO-032

TARGET MARKETS/APPLICATIONS

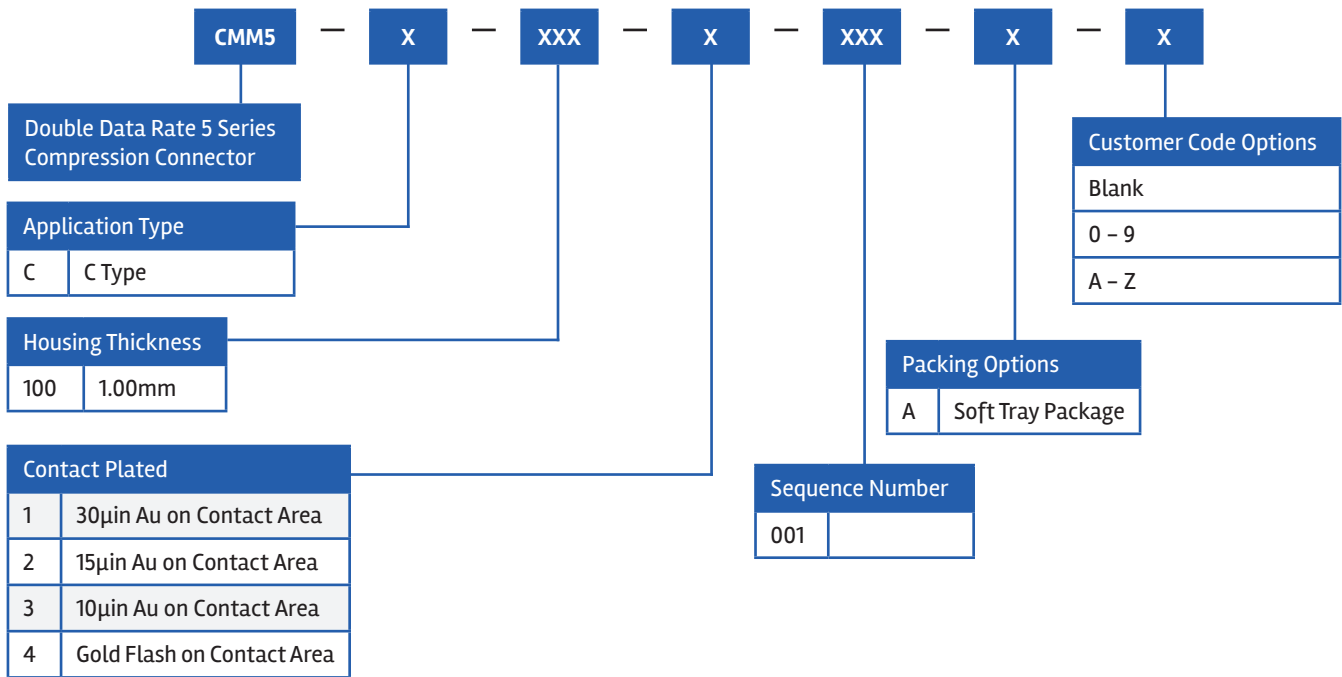


AIPC
Desktop PCs
Workstations
Server



Embedded Systems

PART NUMBER SELECTOR – CONNECTOR



PART NUMBER SELECTOR – TOP COVER



PART NUMBER SELECTOR – BACK PLATE



1	H=1.60 (System Board Thickness: 0.80)
2	H=1.70 (System Board Thickness: 0.90)
3	H=1.80 (System Board Thickness: 1.00)
4	H=1.90 (System Board Thickness: 1.10)
5	H=2.00 (System Board Thickness: 1.20)